

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Amitay Levi, Gian Sharma

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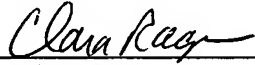
Examiner: To Be Assigned

Title: METHOD OF CMP PLANARIZING WAFER TOPOLOGY

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I hereby certify that this paper is being deposited with the United States Postal Service "EXPRESS MAIL Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to BOX PATENT APPLICATION, Commissioner of Patents and Trademarks; Washington, DC 20231.



Clara Ragan

PRELIMINARY AMENDMENT

BOX PATENT APPLICATION

Assistant Commissioner for Patents

Washington, DC 20231

Sir/Madam:

Prior to prosecution of the above-identified application, please amend this application as follows:

Please add the following claims:

2. A method of polishing a first material on a second material of a semiconductor die, wherein said die having a planar surface, said method comprising:

forming a layer of said second material on said planar surface wherein said layer of said second material having a top surface, substantially parallel to said planar surface;

forming a layer of said first material on said top surface, wherein said layer of said first material varying in a height direction above said top surface;

forming a mask across the die, wherein said mask having a plurality of locations with